



# PVI-3 HR100S

## Photo Imageable Dielectric Material

### Key Application

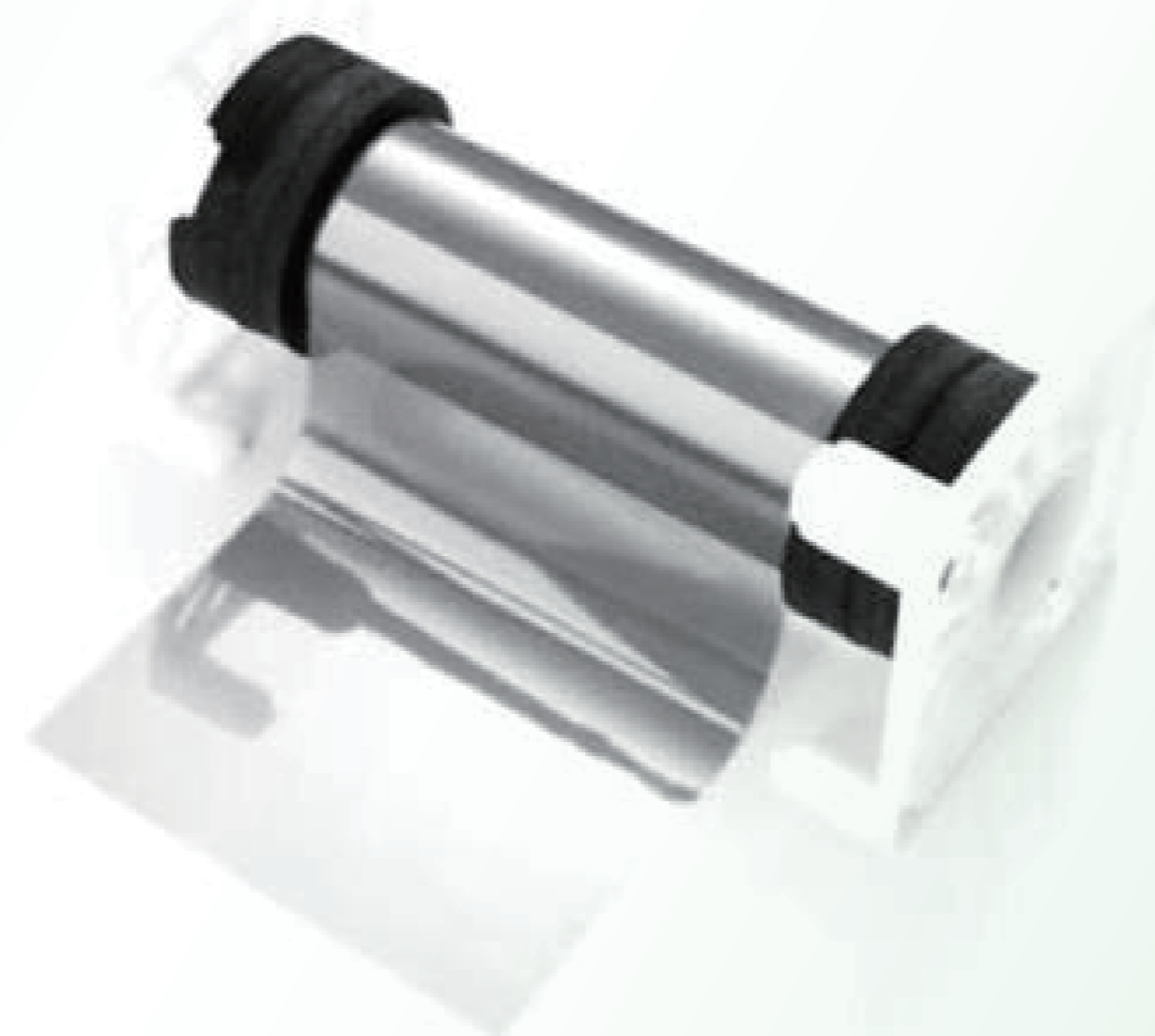
- Next Generation Substrate
- Embedded Substrate
- Si / Grass Interposer
- WLP / PLP

### Product Feature

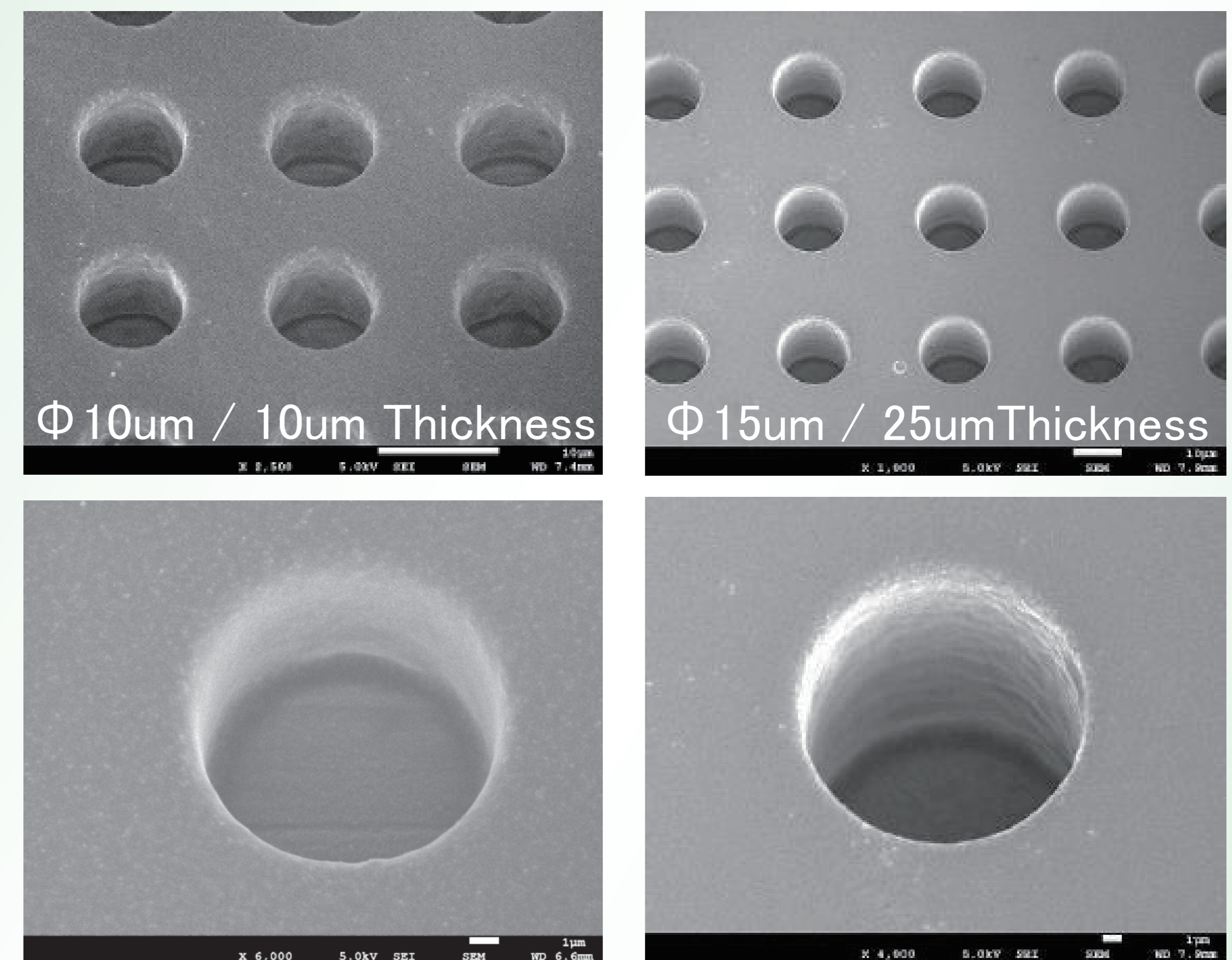
- Dry Film Type
- Negative Type Photosensitive
- Low Curing Temperature (180deg.C)
- Low Shrinkage Curable
- Low Residual Stress
- Excellent Insulation Performance
- Good Resolution
- i-line / h-line Compatible

### Key Benefit of Dry Film

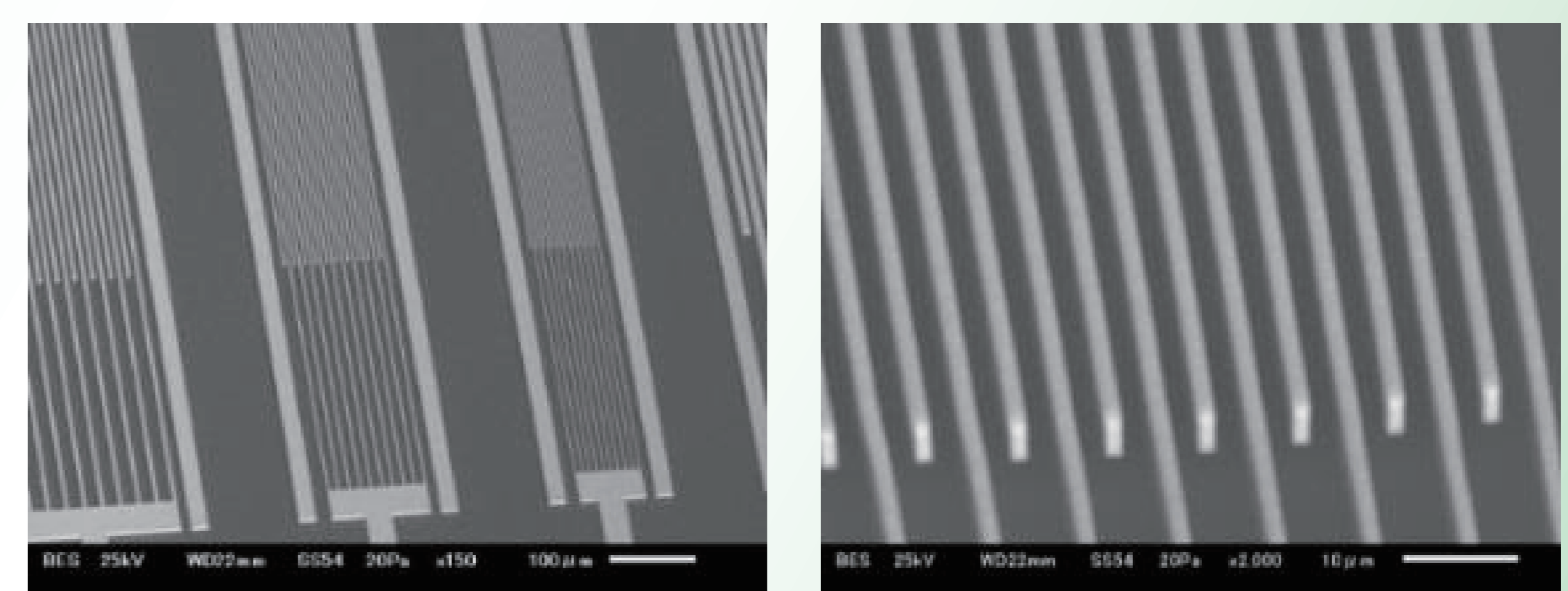
- Large Area Production
- Low Emission—No Need for Spin Coating
- Absorbability of Level Differences (Topography)
- Improved TTV (Uniformity)
- Tenting Compatible



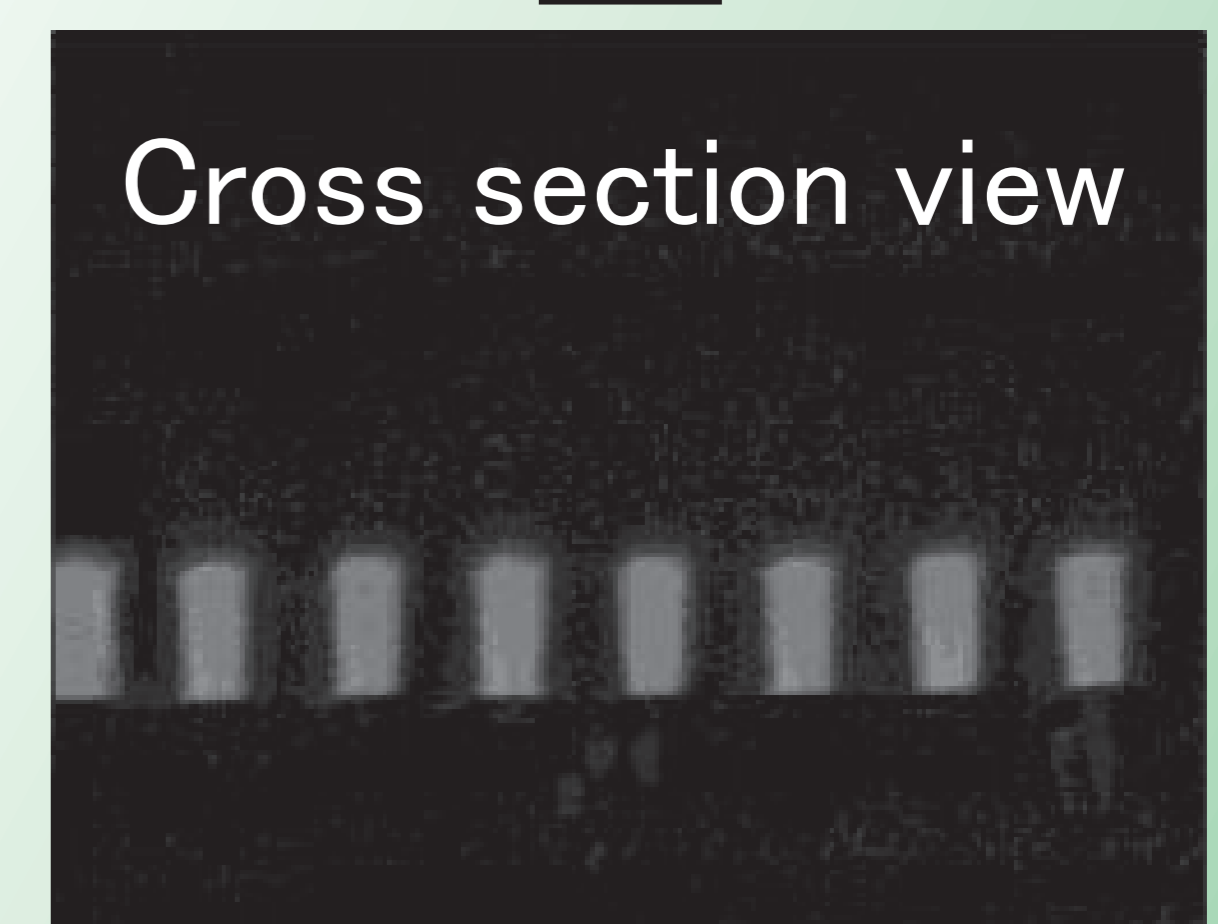
### Resolution



### 2um Line on PID



### Cross section view



### Properties

T <sub>g</sub> (@TMA)	180–185 deg.C
CTE $\alpha 1 / \alpha 2$	40–45 / 130–140 ppm
Elastic Modulus	3.0–3.5 GPa
Elongation	12.0–15.0%

